PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT7789630

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
CHUN-HSIANG HSU	02/04/2023
YEN-HAO LIN	02/04/2023
WEI-HSUAN CHENG	02/04/2023

RECEIVING PARTY DATA

Name:	CORETRONIC CORPORATION
Street Address:	NO. 11, LI-HSIN RD., HSINCHU SCIENCE PARK,
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	18164633

CORRESPONDENCE DATA

Fax Number: (949)391-4699

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 886223692800
Email: usa@jcipgroup.com
Correspondent Name: JCIPRNET
Address Line 1: 8F-1, NO. 100, ROOSEVELT RD. SEC. 2,
Address Line 4: TAIPEI, TAIWAN 100404

ATTORNEY DOCKET NUMBER:	113045-US-PA
NAME OF SUBMITTER:	JAI-WEI CHEN
SIGNATURE:	/Jai-Wei Chen/
DATE SIGNED:	02/09/2023

Total Attachments: 2
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ASSIGNMENT

WHEREAS,

1.Chun-Hsiang Hsu **2.Yen-Hao Lin**
3.Wei-Hsuan Cheng

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **BACKLIGHT MODULE**

[ ] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, 1. Coretronic Corporation
of No. 11, Li-Hsin Rd., Hsinchu Science Park, Hsin-Chu 300,
Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have assigned and transferred, and by these presents does/do assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

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ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Chun-Hsiang Hsu Date: Feb. 4, 2023

Sole or First Joint Inventor: **Chun-Hsiang Hsu**

Signature: Yen - Hao Lin Date: Feb. 4, 2023

Second Joint Inventor (if any): **Yen-Hao Lin**

Signature: Wei - Hsuan Cheng Date: Feb. 4, 2023

Third Joint Inventor (if any): **Wei-Hsuan Cheng**